

10 9 8 7 6 5 4 3 2 1

F

F

E

E

D

D

C

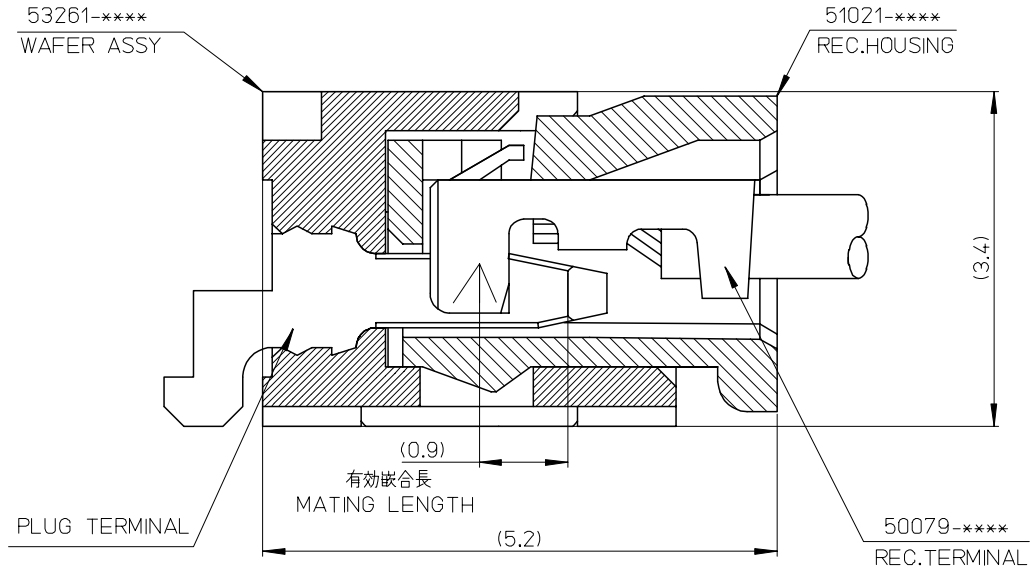
C

B

B

A

A



53261-****	WAFER ASSY	MODEL NO./MATERIAL NO.
50079-****	TERMINAL	
51021-****	HOUSING	

RELEASED EC NO: J2006-2426 DRWN: A0YAGI 2006/02/02 CHKD: YMAEDA 2006/02/03 APPR: NUKITA 2006/02/07	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE ---	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION	
	10 UNDER	± ---	DRAWN BY Y. A0YAGI	DATE 2006/01/30	TITLE 1.25 W-TO-B CONN. 51021,53261 MATING CROSS SECTION			
	10 OVER 30 UNDER	± ---	CHECKED BY Y. MAEDA	DATE 2006/01/30	APPROVED BY N. UKITA			
	30 OVER	± ---	APPROVED BY N. UKITA		DATE 2006/01/30	MOLEX INCORPORATED		
	ANGULAR	± --- °	MATERIAL NO. SEE CHART		DOCUMENT NO. SD-51021-002	SHEET NO. 1 OF 1		
0	DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SIZE A3		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION			

9

8

7

6

5

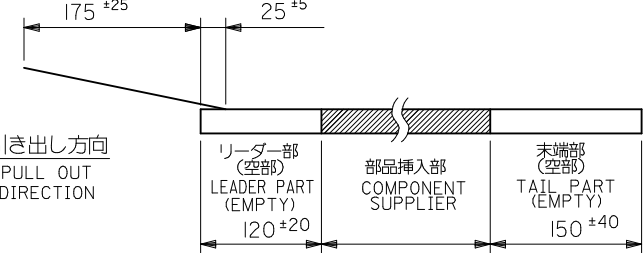
4

3

2

注記  
NOTES

- 53261-\*\*-19 の詳細寸法については図面 SD-53261-024 を参照下さい。  
RE DETAILED DIMENSIONS, SEE SD-53261-024
- 梱包数量: 1000個/リール  
NUMBER OF CONNECTOR: 1000PCS/REEL
- リードテープ長さ LEAD TAPE LENGTH  
トップテープリーダー部 TOP TAPE LEADER PART  
トップテープ未接着部 TOP TAPE NON-BONDED PART



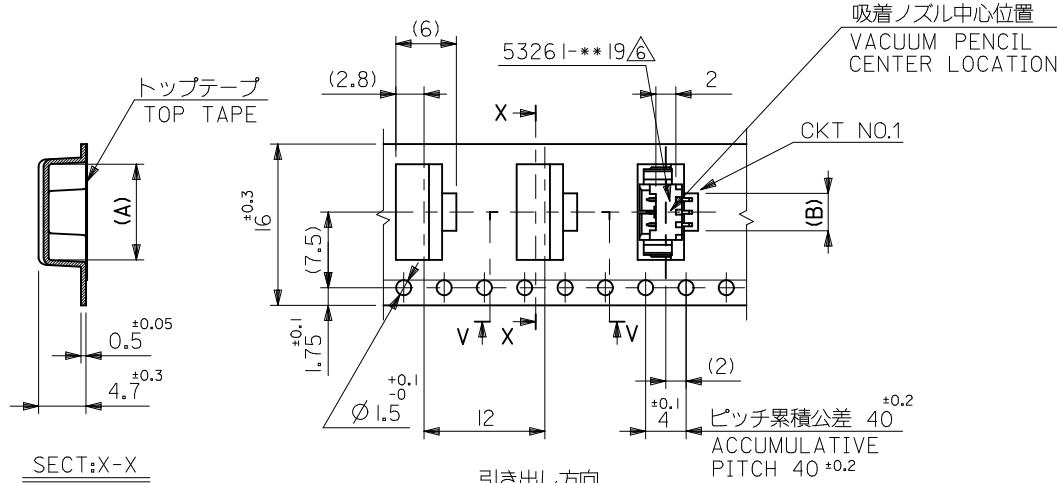
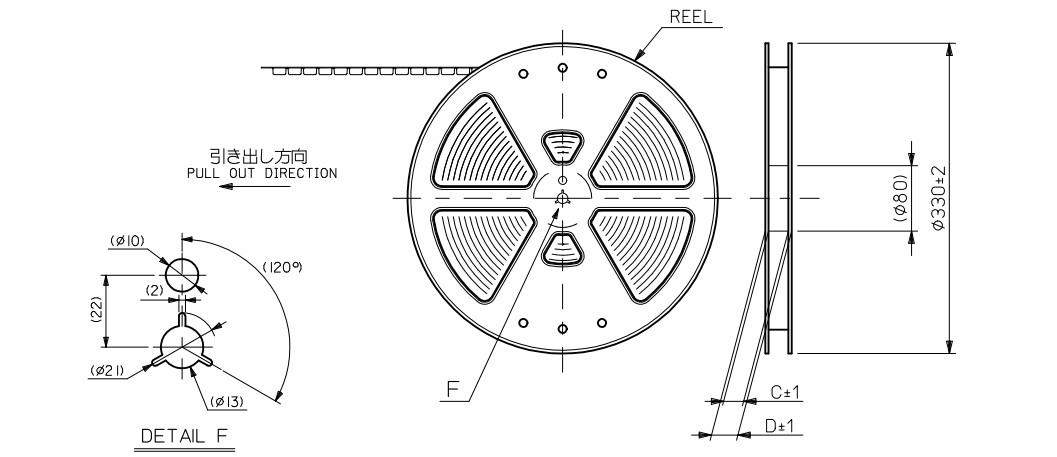
- 材料 (MATERIAL)  
キャリアテープ (CARRIER TAPE): ポリプロピレン (POLYPROPYLENE)  
トップテープ (TOP TAPE): PET, PE, PEF  
リール (REEL): ポリスチレン (PS) <リサイクル材含む>  
POLYSTYRENE (PS) <RECYCLE MATERIAL CONTAINED>

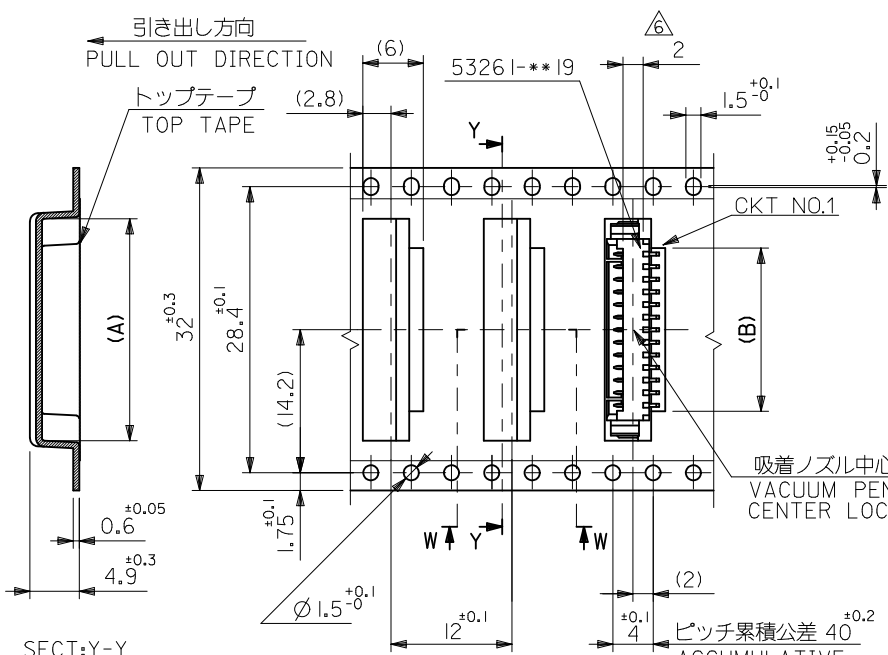
△ コネクタ、ハウジング平面部  
CONNECTOR, HOUSING FLAT AREA

- 本製品は 53261-\*\*-90 の鉛フリー品である。  
THIS PRODUCT IS LEAD FREE OF 53261-\*\*-90
- ELV及びRoHS適合品  
ELV AND RoHS COMPLIANT
- 本製品は乾燥剤入り、ハイバリア梱包仕様である。  
THIS PRODUCT IS HIGH BARRIER PACKAGE WITH DESICCANT.

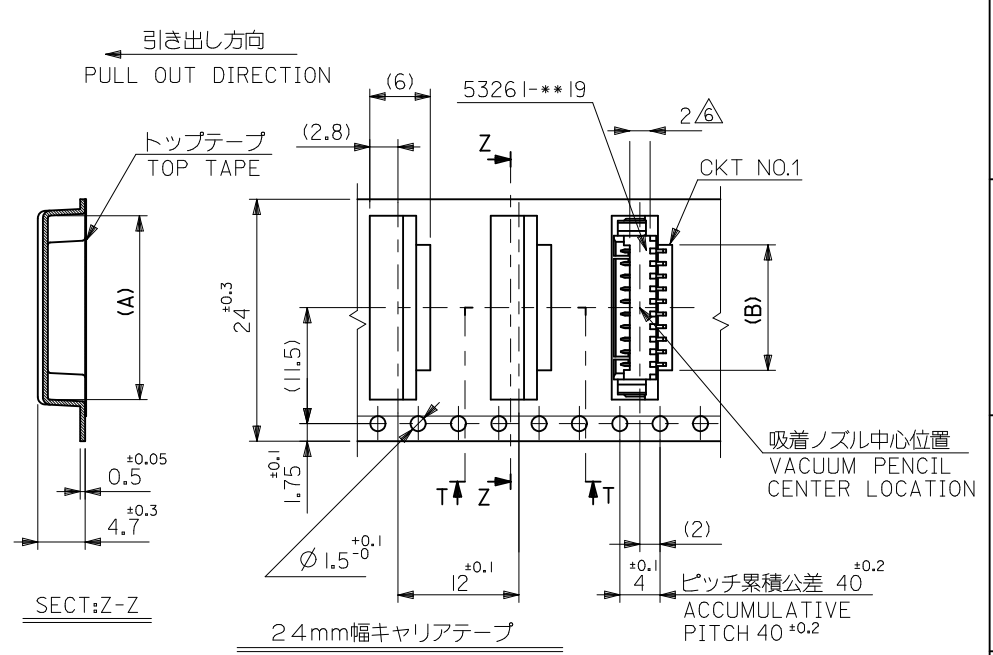
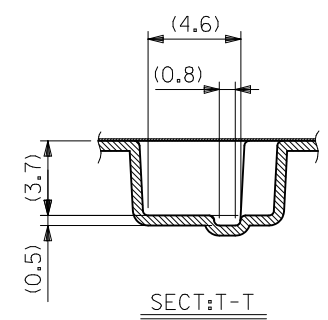
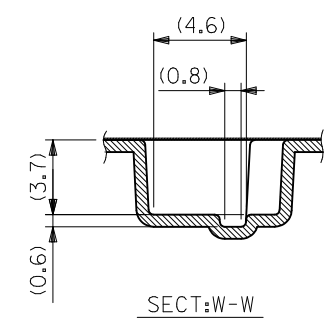
16	21.4	17.4	3.7	9.5	53261-0371	3
			2.45	8.25	53261-0271	2
キャリアテープ幅 CARRIER TAPE WIDTH					D	C
					B	A
					EMBOSSD TAPE PACKAGE 極数 オーダー番号 ORDER NO. CKT.	

REVISED EC NO: D	DESCRIPTION 2010/02/17 DRWN: YGOTO CHKD: KASAKAWA APPR:	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE ---	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION	
		10 UNDER	±0.2	DRAWN BY H. SHIMABUKUR	DATE '04/02/06	TITLE 1.25 W/B CONN WAFER ASSY FOR SMT EMBSTP PKG			
		10 OVER 30 UNDER	±0.25	CHECKED BY K. TOJO	DATE '04/02/06				
		30 OVER	±0.3	APPROVED BY NUKITA	DATE 2010/02/18				
ANGULAR ±3 °		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		MATERIAL NO. SEE TABLE & SHEET 2,3		DOCUMENT NO. SD-53261-023		SHEET NO. 1 OF 3	
SIZE A3		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION							





32mm幅キャリアテープ  
32mm WIDTH CARRIER TAPE

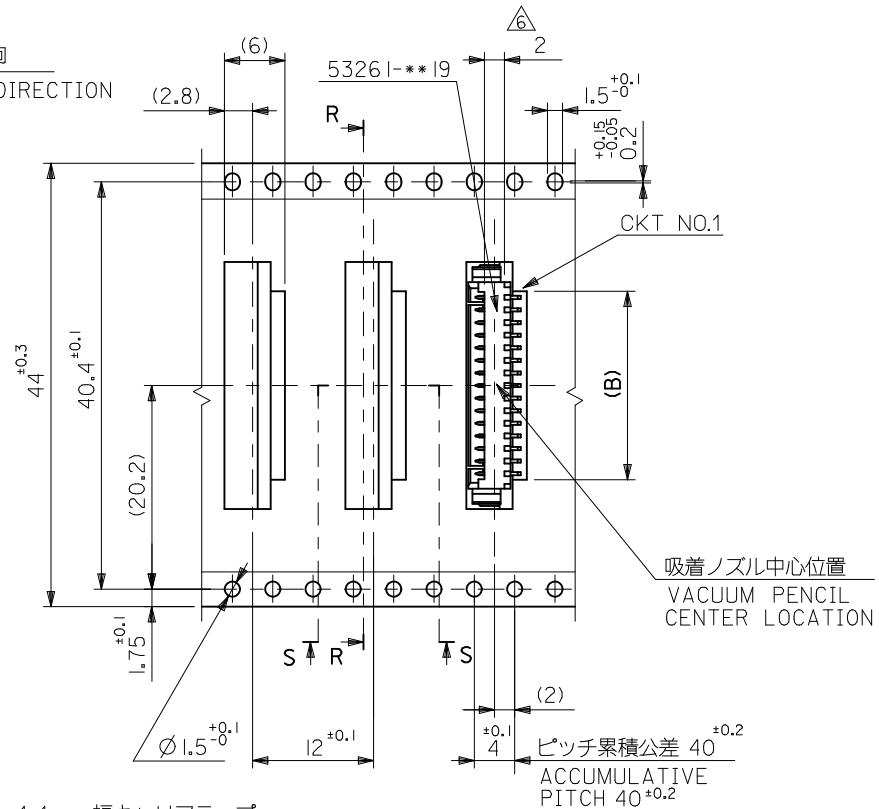
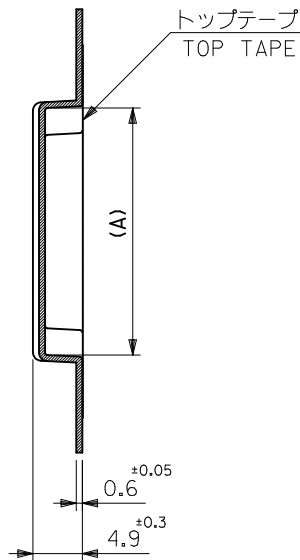


24mm幅キャリアテープ  
24mm WIDTH CARRIER TAPE

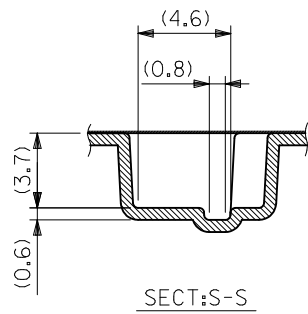
32	37.4	33.4	16.2	22	53261-1371	13
			14.95	20.75	-1271	12
			13.7	19.5	-1171	11
			12.45	18.25	-1071	10
24	29.4	25.4	11.2	17	-0971	9
			9.95	15.75	-0871	8
			8.7	14.5	-0771	7
			7.45	13.25	-0671	6
			6.2	12	-0571	5
			4.95	10.75	-0471	4

MODEL NO.	53261-***71	キャリアテープ幅 CARRIER TAPE WIDTH	D	C	B	A	EMBOSSD TAPE PACKAGE オーダー番号 ORDER NO.	極数 CKT.
REVISED	2010/02/17	GENERAL TOLERANCES (UNLESS SPECIFIED)	DIMENSION STYLE MM ONLY			SCALE ---	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION
EC NO.	DRWN:YGOITO CHKD:KASAKAWA APPR:	10 UNDER ±0.2	DRAWN BY H. SHIMABUKUR	DATE '04/02/06	TITLE 1.25 W/B CONN WAFER ASSY FOR SMT EMBSTP PKG			
		10 OVER 30 UNDER ±0.25	CHECKED BY K. TOJO	DATE '04/02/06	MOLEX INCORPORATED			
		30 OVER ±0.3	APPROVED BY NUKITA	DATE 2010/02/18	DOCUMENT NO. SD-53261-023			SHEET NO. 2 OF 3
		ANGULAR ±3 °	SEE TABLE & SHEET 1.3					
		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION					

引き出し方向  
PULL OUT DIRECTION

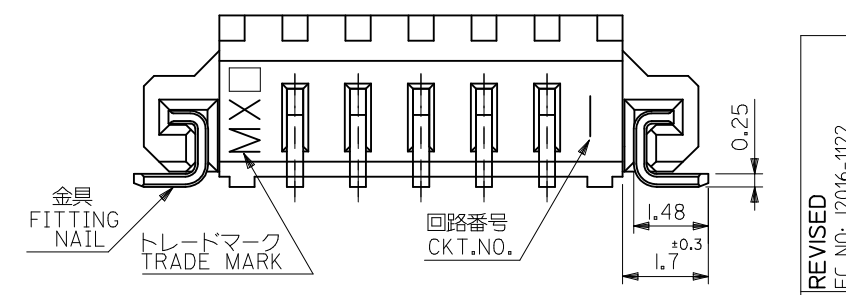
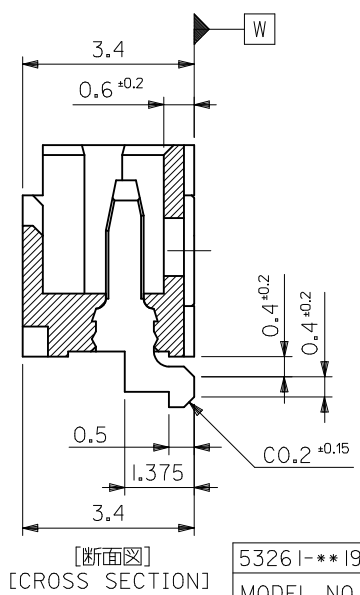
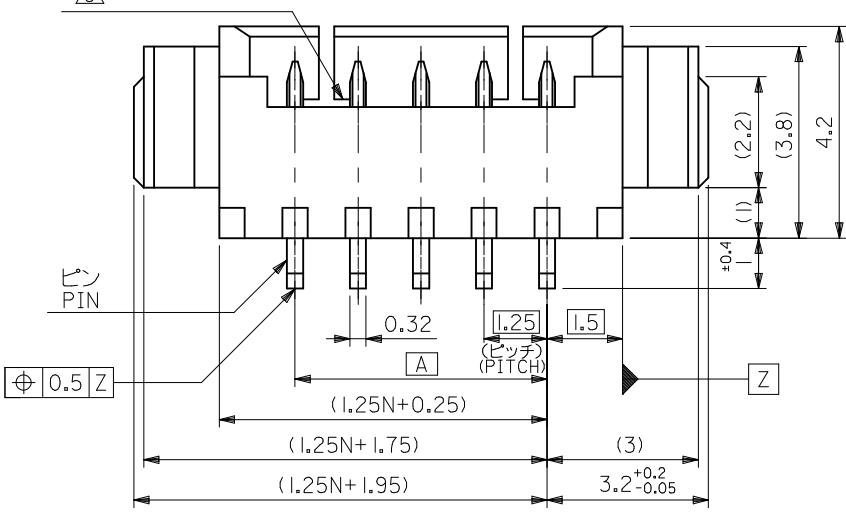
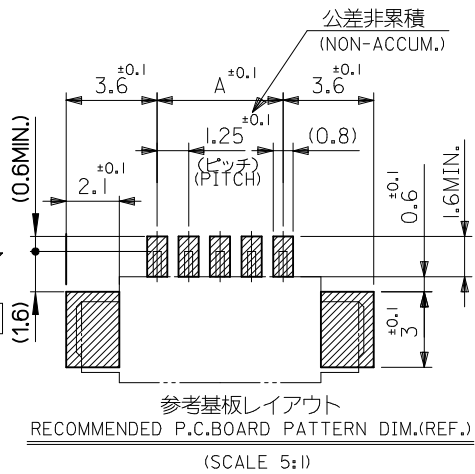
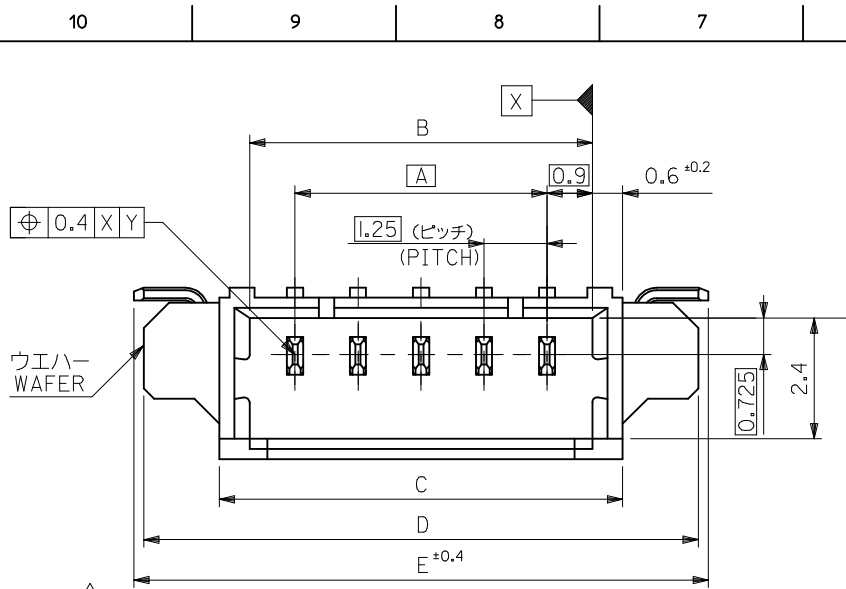


44mm幅キャリアテープ  
44mm WIDTH CARRIER TAPE



44	49.4	45.4	18.7	24.5	53261-1571	15				
			17.45	23.25	53261-1471	14				
キャリアテープ幅 CARRIER TAPE WIDTH					D	C	B	A	EMBOSSD TAPE PACKAGE	極数 CKT.
MODEL NO. 53261-***71					ORDER NO.					

REVISED EC NO: D DRWN:Y.GOTO CHKD:KASAKAWA APPR: REV	DESCRIPTION	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE ---	DESIGN UNITS METRIC		THIRD ANGLE PROJECTION	
	2010/02/17	10 UNDER	±0.2	DRAWN BY	DATE	TITLE				
		10 OVER 30 UNDER	±0.25	H. SHIMABUKUR	'04/02/06	1.25 W/B CONN WAFER ASSY FOR SMT EMBSTP PKG				
		30 OVER	±0.3	CHECKED BY	DATE					
		ANGULAR	±3 °	K. TOJO	'04/02/06	APPROVED BY				
		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		NUKITA	2010/02/18	MATERIAL NO.		MOLEX INCORPORATED		
				SEE TABLE & SHEET 12		DOCUMENT NO.		SD-53261-023		
				SIZE	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION					



注記 NOTES

- 嵌合相手: 51021 シリーズ  
MATES WITH: 51021 SERIES
- 材質 MATERIAL  
ウエハー: NYLON46, UL94V-0  
ピン: リン青銅  
: PHOS-BRO  
: 銅メッキ 1.0 マイクロメートル以上  
: TIN 1.0 MICROMETER MINIMUM  
: ニッケル下地 1.0 マイクロメートル以上  
: NICKEL (UNDER PLATING) 1.0 MICROMETER MINIMUM  
金具  
FITTING NAIL: リン青銅  
: PHOS-BRO  
: 銅メッキ 1.0 マイクロメートル以上  
: TIN 1.0 MICROMETER MINIMUM  
: ニッケル下地 1.0 マイクロメートル以上  
: NICKEL (UNDER PLATING) 1.0 MICROMETER MINIMUM
- ロック窓は2、3極は1箇所、4極以上は2箇所とする。  
LOCKING WINDOW: ONE PLACE FOR 2 AND 3 CKT. AND TWO PLACES FOR MORE THAN 3 CKT.
- ソリダール部のスレ量及び金具(補強板)のスレ量は基準面 W に対し、上方向 0.05MAX.、下方向に 0.1 MAX.とする。  
OFFSET BETWEEN BASIS PLANE W TO SOLDER TAIL BOTTOM AND FITTING NAIL BOTTOM:  
UPPER SIDE: 0.05MAX.  
LOWER SIDE: 0.1MAX.
- 本製品は 53261-\*\*-10 の鉛フリー品である。  
THIS PRODUCT IS LEAD FREE OF 53261-\*\*10
- ELV及びRoHS適合品  
ELV AND RoHS COMPLIANT.
- ソルダール部及び金具の平坦度は0.1以下。  
SOLDER TAIL & FITTING NAIL COPLANARITY TO BE 0.1 MAX.

26.4	26	23	21.8	20	53261-1771	53261-1719	17	
23.9	23.5	20.5	19.3	17.5	-1571	-1519	15	
22.65	22.25	19.25	18.05	16.25	-1471	-1419	14	
21.4	21	18	16.8	15	-1371	-1319	13	
20.15	19.75	16.75	15.55	13.75	-1271	-1219	12	
18.9	18.5	15.5	14.3	12.5	-1171	-1119	11	
17.65	17.25	14.25	13.05	11.25	-1071	-1019	10	
16.4	16	13	11.8	10	-0971	-0919	9	
15.15	14.75	11.75	10.55	8.75	-0871	-0819	8	
13.9	13.5	10.5	9.3	7.5	-0771	-0719	7	
12.65	12.25	9.25	8.05	6.25	-0671	-0619	6	
11.4	11	8	6.8	5	-0571	-0519	5	
10.15	9.75	6.75	5.55	3.75	-0471	-0419	4	
8.9	8.5	5.5	4.3	2.5	-0371	-0319	3	
53261-**-19	7.65	7.25	4.25	3.05	1.25	53261-0271	53261-0219	2

REVISED EC NO: J2016-1122 DRWN: QHEJ1 CHKD: SAKIYAMA APPR: IKANEKO	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE		SCALE	DESIGN UNITS		THIRD ANGLE PROJECTION	
	0.25 UNDER	UNDER	±0.03	MM ONLY		10:1	METRIC		◎
	0.25 OVER	0.5 UNDER	±0.05	DRAWN BY	DATE	TITLE			
	0.5 OVER	1.0 UNDER	±0.1	HS HIMABU	04/02/06	1.25 WIRE TO BOARD WAFER ASS FOR SMT			
1.0 OVER	10 UNDER	±0.2	CHECKED BY	DATE	molex				
10 OVER	30 UNDER	±0.25	KTOJO	04/02/06					
30 OVER		±0.3	APPROVED BY	DATE	DOCUMENT NO.		SHEET NO.		
ANGULAR	±3 °		MSASAO	04/02/06	SD-53261-024		1 OF 1		
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS			SIZE		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX ELECTRONIC TECHNOLOGIES, LLC AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION				
			A3						